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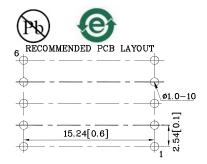
Part Number: XDDGK14A

14.2mm (0.56") SINGLE DIGIT NUMERIC DIS-**PLAY**



Features

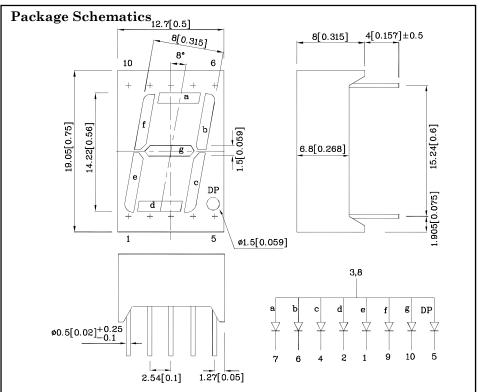
- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white
- ullet Optional black face provides superior color contrast
- RoHS Compliant





ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.

2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		DGK (InGaN)	Unit
Reverse Voltage	$V_{\rm R}$	5	V
Forward Current	I_{F}	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA
Power Dissipation	P_{D}	102.5	mW
Operating Temperature	T_{A}	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		450	V
Lead Solder Temperature [2mm Below Package Base]	260°C		

Operating Characteristics (T_A =25°C)		DGK (InGaN)	Unit
Forward Voltage (Typ.) (I_F =10mA)	3	V	
Forward Voltage (Max.) (I _F =10mA)	4.1	V	
Reverse Current (Max.) (V_R =5 V)	I_{R}	50	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	515*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	525*	nm
Spectral Line Full Width At Half-Maximum (Typ.) △ (I _F =10mA)		35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	рF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XDDGK14A	Green	InGaN		49990 1990*	515*	Common Anode, Rt. Hand Decimal.

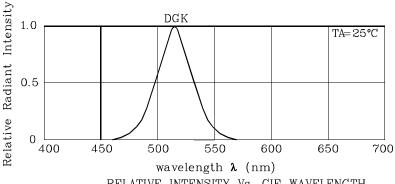
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Jan 17,2014

XDSB7546 V2-X Layout: Maggie L.

Part Number: XDDGK14A

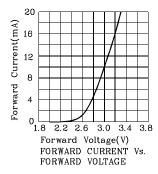
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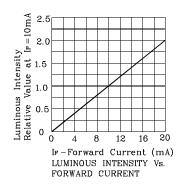


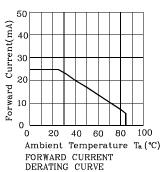


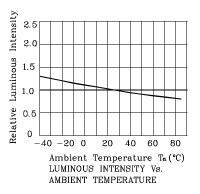
RELATIVE INTENSITY Vs. CIE WAVELENGTH

♦ DGK

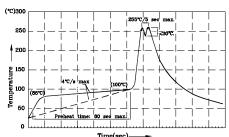








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- nmend pre-heat temperature of 105°C or less (as measured with a noccupie attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 250°C wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec
- 2.Peak wave soldering temperature betweenax).
 3.Do not apply stress to the epoxy resin d.Fixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

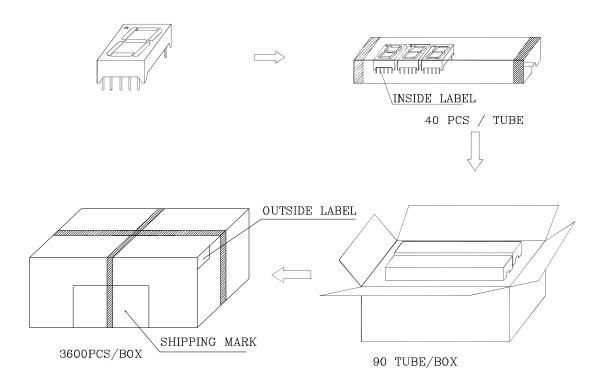
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

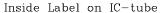
Note: Accuracy may depend on the sorting parameters.

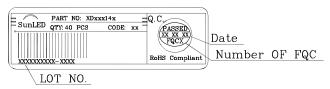


$14.2\mathrm{mm}$ (0.56") SINGLE DIGIT NUMERIC DISPLAY

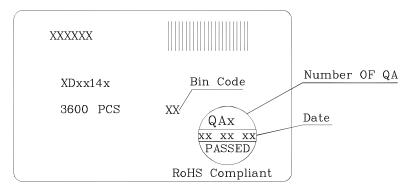
PACKING & LABEL SPECIFICATIONS







Outside Label on Box



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

Jan 17,2014